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Applicants: Yoo, Woo Sik  
Assignee: WaferMasters, Inc.  
Title: Method for Ultra-Thin Film Formation  
Serial No.: 09/775,835 Filing Date: January 31, 2001  
Examiner: Lisa A. Kilday Group Art Unit: 2829  
Docket No.: M-8250 US

Irvine, California  
July 03, 2002

BOX AMENDMENT  
COMMISSIONER FOR PATENTS  
Washington, D. C. 20231

RESPONSE TO NON-FINAL OFFICE ACTION

Dear Sir:

In response to the Office Action dated April 4, 2002, Applicants submit the following amendments and remarks.

IN THE CLAIMS

The following is a clean version of the entire set of pending claims. In accordance with 37 C.F.R. §1.121(c)(1)(ii), Attachment A provides a marked-up version of the claims containing the newly introduced changes.

Please amend Claims 1-5, 7, 8, 10, 11, 13-16 and 19-20.

1. (Amended) A method for forming a thin film on a semiconductor wafer comprising:
- heating an internal environment of a process chamber to a steady-state processing temperature;
  - loading a semiconductor wafer into said internal environment of said process chamber;

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